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Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	$\epsilon_r$	Loss Tangent	Impedance ID
3		FR4 Core	Plane	35.000	35.000				
4		Signal	200.000	200.000	45.000	4.200	0.0195		
		PrePreg 1080	Signal	35.000	35.000				
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
5		FR4 Core	Plane	35.000	35.000				
6		FR4 Core	Plane	200.000	200.000	45.000	4.200	0.0000	
		PrePreg 1080	Plane	35.000	35.000				
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
	PrePreg 1080		65.670	65.670	60.000	4.200	0.0195		
	PrePreg 1080		65.670	65.670	60.000	4.200	0.0195		
7	Signal	Signal	35.000	35.000					
8	FR4 Core	Signal	35.000	35.000	45.000	4.200	0.0195		
	FR4 Core	Plane	200.000	200.000					
	FR4 Core	Plane	35.000	35.000					

Copper Thickness = 210.000 | Dielectric Thickness = 994.020 | Solder Mask Thickness = 0.000 | Stack Up Thickness = 1204.020 | Stack Up Thickness with Soldermask = 1204.020  
 Stack Up Cost = 25.00

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost
Polar Samples	SM/001	Liquid PhotoImageable Mask	SolderMask	500-001	2	0.50	1.00	2	1.00
Polar Samples	FO/001	Copper Foil	Copper	100-001	4	1.00	4.00	4	4.00
Polar Samples	PP/003	PrePreg 3113	Dielectric	300-003	2	1.00	2.00	2	2.00
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	8	1.00	8.00	8	8.00
Polar Samples	CO/017	FR4 Core	FR4	400-017	3	2.00	6.00	3	6.00
							21.00		21.00

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 21.00 |

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Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	$\epsilon_r$	Loss Tangent	Impedance ID
2		Copper Foil	Signal	18.000	18.000				
		PrePreg 1080		75.000	75.000	60.000	4.200	0.0195	
3			Plane	35.000	35.000				
		FR4 Core		200.000	200.000	45.000	4.200	0.0195	
4			Signal	35.000	35.000				
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
5			Plane	35.000	35.000				
		FR4 Core		200.000	200.000	45.000	4.200	0.0000	
6			Plane	35.000	35.000				
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
7			Signal	35.000	35.000				
		FR4 Core		200.000	200.000	45.000	4.200	0.0195	
8			Plane	35.000	35.000				
		PrePreg 1080		75.000	75.000	60.000	4.200	0.0195	
9		Copper Foil	Signal	18.000	18.000				

Copper Thickness = 246.000 | Dielectric Thickness = 1144.020 | Solder Mask Thickness = 0.000 | Stack Up Thickness = 1390.020 | Stack Up Thickness with Soldermask = 1390.020  
 Stack Up Cost = 29.00

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost
Polar Samples	SM/001	Liquid Photolmageable Mask	SolderMask	500-001	2	0.50	1.00	2	1.00
Polar Samples	FO/001	Copper Foil	Copper	100-001	4	1.00	4.00	4	4.00
Polar Samples	PP/003	PrePreg 3113	Dielectric	300-003	2	1.00	2.00	2	2.00
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	8	1.00	8.00	8	8.00
Polar Samples	CO/017	FR4 Core	FR4	400-017	3	2.00	6.00	3	6.00
							21.00		21.00

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 21.00 |

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Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	$\epsilon_r$	Loss Tangent	Impedance ID
1		Liquid Photolmageable Mask			25.400		4.000	0.0000	
2		Copper Foil	Signal	18.000	18.000				
3		PrePreg 3113		88.500	88.500	53.000	4.200	0.0195	
4		Copper Foil	Signal	18.000	18.000				
5		PrePreg 1080		75.000	75.000	60.000	4.200	0.0195	
6		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
7		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
8		FR4 Core	Plane	35.000	35.000				
9		FR4 Core	Plane	200.000	200.000	45.000	4.200	0.0195	
10		FR4 Core	Plane	35.000	35.000				
11		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
12		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
13		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
14		FR4 Core	Plane	35.000	35.000				
15		FR4 Core	Plane	200.000	200.000	45.000	4.200	0.0000	
16		FR4 Core	Plane	35.000	35.000				
17		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
18		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
19		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
20		Copper Foil	Signal	35.000	35.000				
21		FR4 Core	Signal	200.000	200.000	45.000	4.200	0.0195	
22		FR4 Core	Plane	35.000	35.000				
23		PrePreg 1080		75.000	75.000	60.000	4.200	0.0195	
24		Copper Foil	Signal	18.000	18.000				
25		PrePreg 3113		88.500	88.500	53.000	4.200	0.0195	
26		Copper Foil	Signal	18.000	18.000				
27		Liquid Photolmageable Mask			25.400		4.000	0.0000	

1603.02

Copper Thickness = 282.000 | Dielectric Thickness = 1321.020 | Solder Mask Thickness = 50.800 | Stack Up Thickness = 1603.020 | Stack Up Thickness with Soldermask = 1653.820  
Stack Up Cost = 35.50

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost
Polar Samples	SM/001	Liquid Photolmageable Mask	SolderMask	500-001	2	0.50	1.00	2	1.00
Polar Samples	FO/001	Copper Foil	Copper	100-001	4	1.00	4.00	4	4.00
Polar Samples	PP/003	PrePreg 3113	Dielectric	300-003	2	1.00	2.00	2	2.00
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	8	1.00	8.00	8	8.00
Polar Samples	CO/017	FR4 Core	FR4	400-017	3	2.00	6.00	3	6.00
							21.00	21.00	

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 21.00 |

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